



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-05-19
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD888T4	CQDP*BI01T62	A	SHENZHEN B/E	2016-05-19
Amount		UoM	Unit type	ST ECOPACK Grade
330.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	CQDP*BI01T62					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.195	mg	supplier	die	Silicon (Si)	7440-21-3		1.163	mg	973222	3524
				supplier	metallization	Aluminium (Al)	7429-90-5		0.015	mg	12552	45
				supplier	Passivation	Silicon Oxide	7631-86-9		0.017	mg	14226	52
Leadframe	Copper & its alloys	164.944	mg	supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	995198	497430
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	2001	1000
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2801	1400
Soft solder	Solder	1.311	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.252	mg	954996	3794
				supplier	solder	Silver (Ag)	7440-22-4		0.033	mg	25172	100
				supplier	solder	Tin (Sn)	7440-31-5		0.026	mg	19832	79
Bonding wires	Other inorganic materials	0.147	mg	supplier	wire	Copper (Cu)	7440-50-8		0.147	mg	1000000	446
Encapsulation	Other Organic Materials	161.358	mg	supplier	mold compound	Silica, vitreous	60676-86-0		141.188	mg	874998	427842
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-b	EC 413-900-7		6.454	mg	39998	19558
				supplier	mold compound	Epoxy Resin	25068-38-6		4.841	mg	30002	14670
				supplier	mold compound	phenol resin	29690-82-2		8.068	mg	50001	24448
				supplier	mold compound	Carbon black	1333-86-4		0.807	mg	5001	2445
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3167